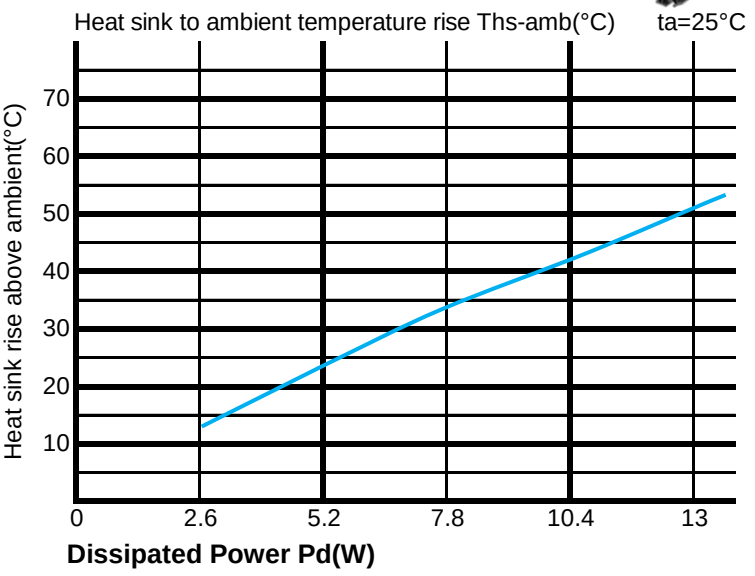
The thermal data table

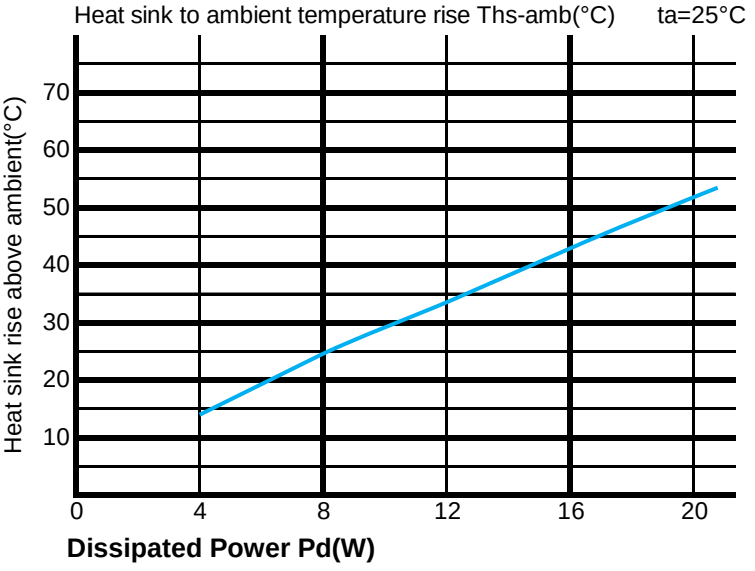
Fan-7020 thermal data

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
		FanLED-7020	FanLED-7020
Dissipated Power Pd(W)	2.6	5.2	14
	5.2	4.5	24.5
	7.8	4.2	34.5
	10.4	3.9	42.4
	13	3.7	50.5



Fan-7050 thermal data

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
		FanLED-7050	FanLED-7050
Dissipated Power Pd(W)	4	3.4	14.5
	8	2.9	25
	12	2.6	34.4
	16	2.5	43
	20	2.3	51



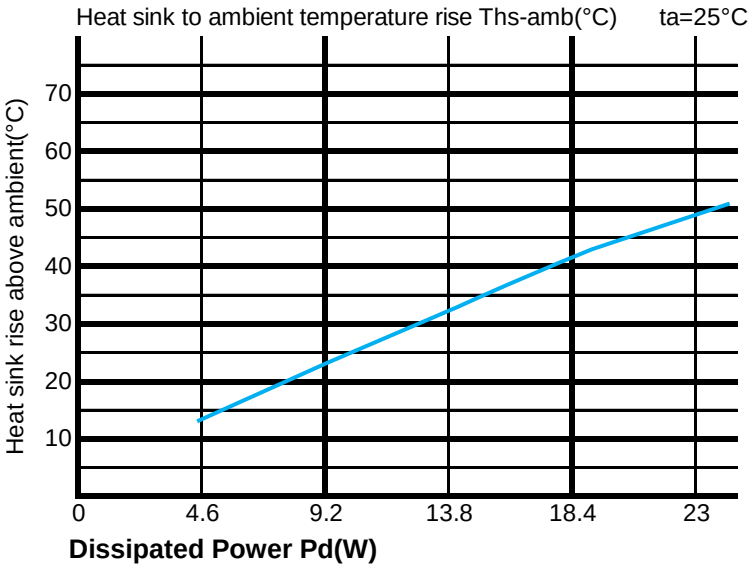
Tel:+86-769-39023131
E-fax:+86-(020)28819702 ext:22122
Email:sales@mingfatech.com
Http://www.heatsinkled.com
Http://www.mingfatech.com

FanLED **FanLED-70 Series Φ70mm Material AL6063-T5 COB Star Heat Sinks Thermal Data**

The thermal data table

Fan-7080 thermal data

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
		FanLED-7080	FanLED-7080
Dissipated Power Pd(W)	4.6	2.8	14
	9.2	2.4	24
	13.8	2.2	33
	18.4	2	41.5
	23	1.9	49



* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

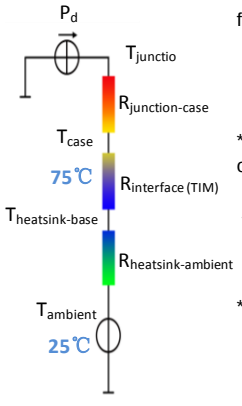
*To calculate the dissipated power please use the following formula: Pd = Pe x (1-ηL).

Pd - Dissipated power ; Pe - Electrical power ; ηL = Light effciency of the LED module;

*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease,A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula: θ ＝(Ths－Ta)/Pd

θ - Thermal Resistance [°C/W] ; Ths - Heatsink temperature ; Ta - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface\ (TIM)}$ [°C/W], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ [°C/W], and the ambient temperature is $T_{ambient}$ [°C].

*Thermal resistances outside the package $R_{interface\ (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point.Thus, the following formula is also used:

$T_{junction}=(R_{junction-case}+R_{case-ambient})\cdot Pd+T_{ambient}$

Tel:+86-769-39023131
E-fax:+86-(020)28819702 ext:22122
Email:sales@mingfatech.com
Http://www.heatsinkled.com
Http://www.mingfatech.com